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Part Number: 0737690100

Status: Active

Overview: HDM Backplane Connector System

Description: HDM Board-to-Board Stacking Header, High Rise Vertical, Press-Fit, Open End Option, 72 Circuits, Stack Height 15.05mm

Documents:

[3D Model](#) [Packaging Specification PK-70873-0870 \(PDF\)](#)

[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

[Product Specification PS-73780-999-001 \(PDF\)](#)

General

Product Family Backplane Connectors

Series 73769

Application Backplane, Mezzanine

Component Type PCB Header

Overview HDM Backplane Connector System

Product Name HDM

UPC 800753948020

Physical

Circuits (Loaded) 72

Circuits (maximum) 72

Color - Resin Black

Durability (mating cycles max) 200

First Mate / Last Break No

Guide to Mating Part No

Keying to Mating Part None

Material - Metal Phosphor Bronze

Material - Plating Mating Gold

Material - Plating Termination Tin-Lead

Material - Resin High Temperature Thermoplastic

Net Weight 12.780/g

Number of Columns 12

Number of Pairs Open Pin Field

Number of Rows 6

Orientation Vertical

PC Tail Length 3.50mm

PCB Locator No

PCB Retention None

PCB Thickness - Recommended 1.40mm

Packaging Type Tube

Pitch - Mating Interface 2.00mm

Plating min - Mating 0.762µm

Plating min - Termination 0.381µm

Polarized to PCB No

Stackable Yes

Surface Mount Compatible (SMC) Yes

Temperature Range - Operating -55° to +105°C

Termination Interface: Style Through Hole - Compliant Pin

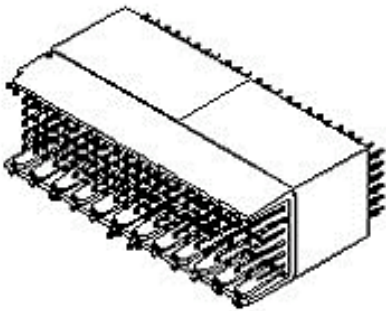
Electrical

Current - Maximum per Contact 1.0A

Data Rate 1.0 Gbps

Real Signals (per 25mm) 72

Voltage - Maximum 100V AC



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant

REACH SVHC
Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free
Status
Low-Halogen

For more information, please visit [Contact US](#)

China ROHS Green Image
ELV Not Relevant
RoHS Phthalates Not Contained

Search Parts in this Series
73769 Series

Mates With
73632 HDM+ Board-to-Board Daughtercard
Receptacle. 73780 HDM Board-to-Board
Daughtercard Receptacle

Application Tooling | FAQ
*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global	
Description	Product #
Backplane Signal Insertion Module Press-In Tool for 2.00mm Pitch HDM* Board-to-Board Backplane Header	622008502

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0870
Product Specification	PS-73780-999-001

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